



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PACKAGE CODE 5042 IS TO ACCOUNT FOR PGE AND THE BUILT-IN HEAT SPREADER.

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TITLE: 668 I/O TEPBGA, HEAT SPREADER, 29 X 29 PKG, 1 MM PITCH	DOCUMENT NO: 98ASA10735D	REV: A
	STANDARD: JEDEC MS-034 AAM-1	
	SOT1744-1	11 MAR 2016